



*AUTO EQUIPMENT
SOLUTION PROVIDER*

萬潤科技

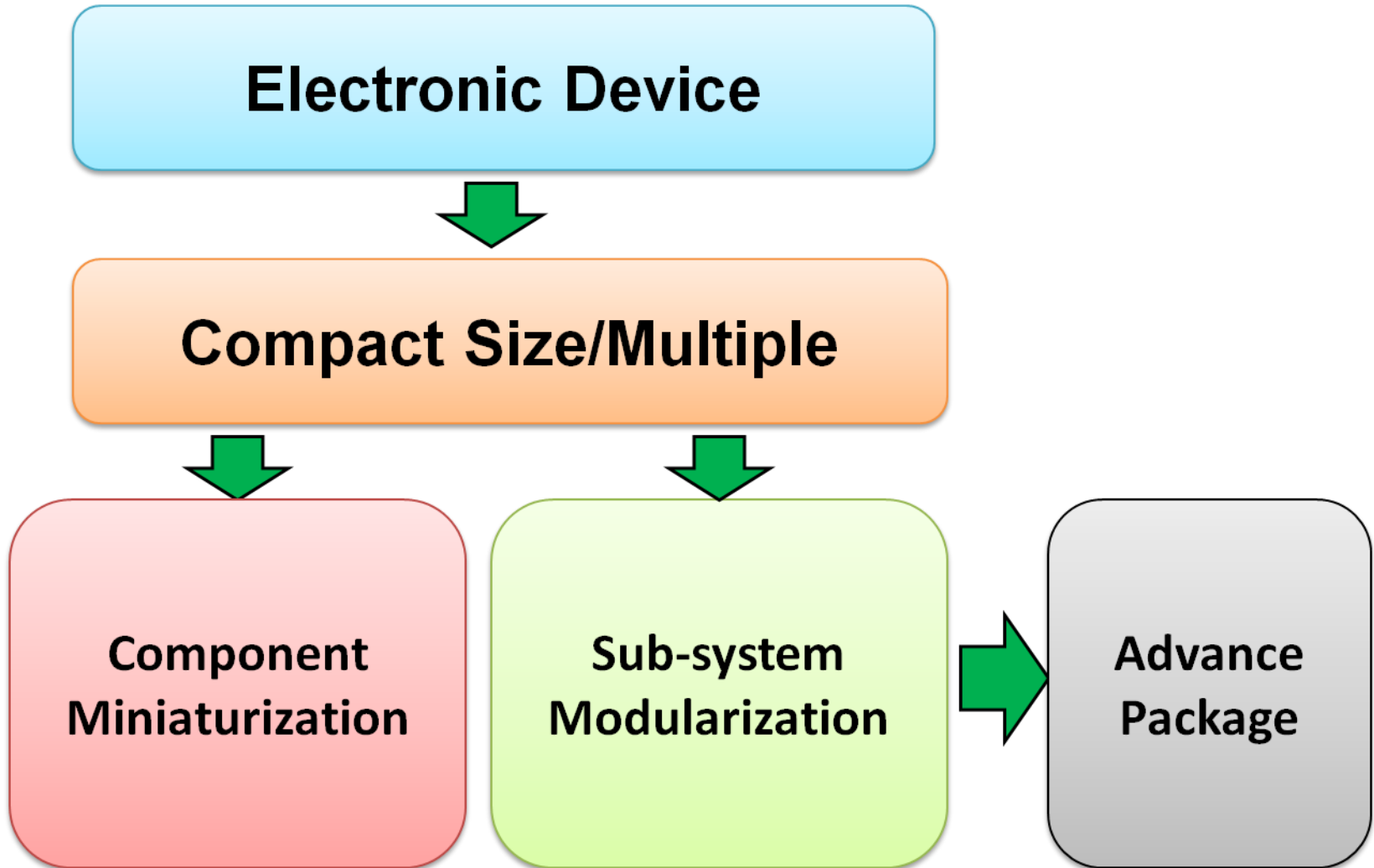
AllRing Tech

Stock Code:6187.TT

Company Profile

Established	May 24, 1996
Capital	NTD 833 Million (USD 27 Million)
Business	Automation equipment supplier for Semiconductor test & package, Passive Component manufacturing industries
Employee	222 (Aug, 2020)
Chairman	Larry Lu
Address	No.1 Luke 10th Rd. ,Lujhu,Kaohsiung,Taiwan
Website	www.allring-tech.com.tw

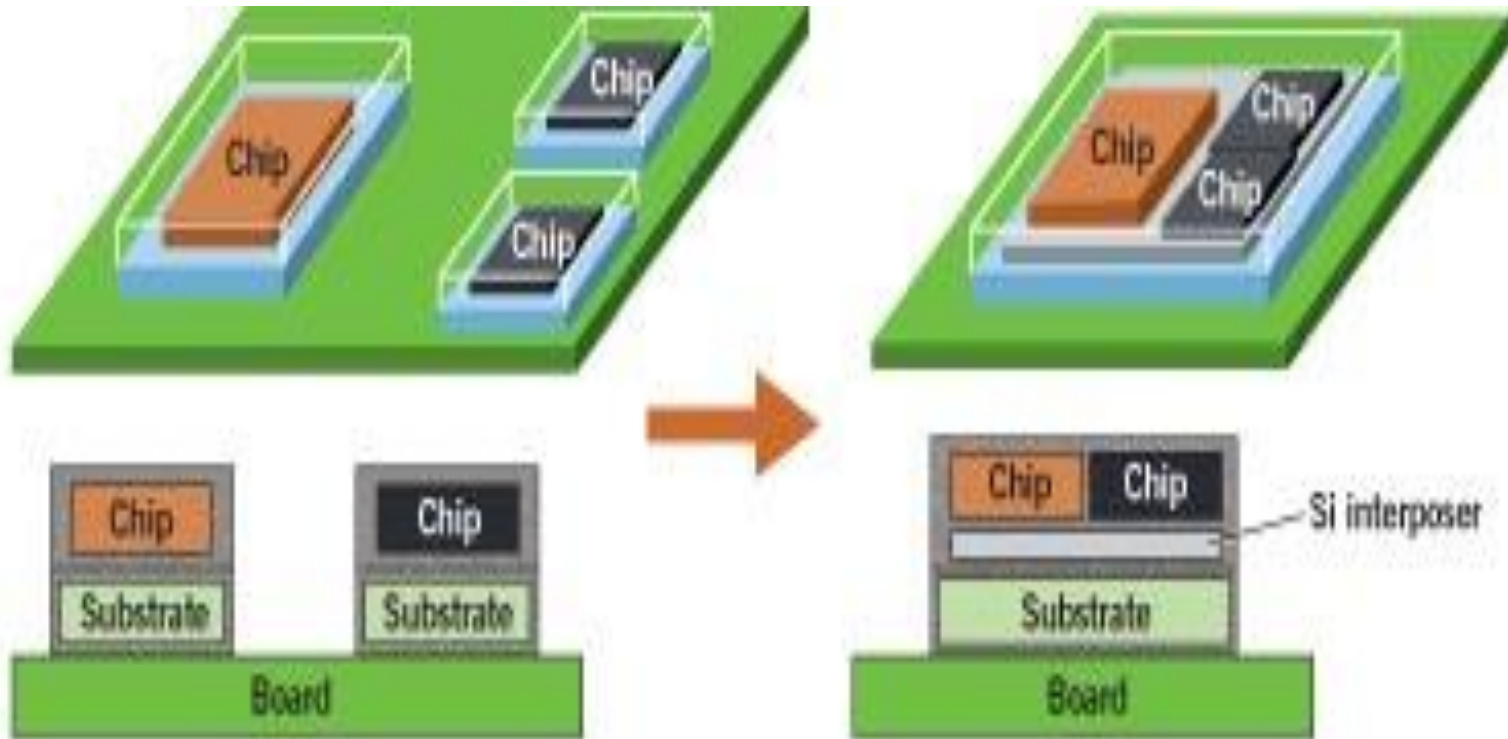
Industry Overview



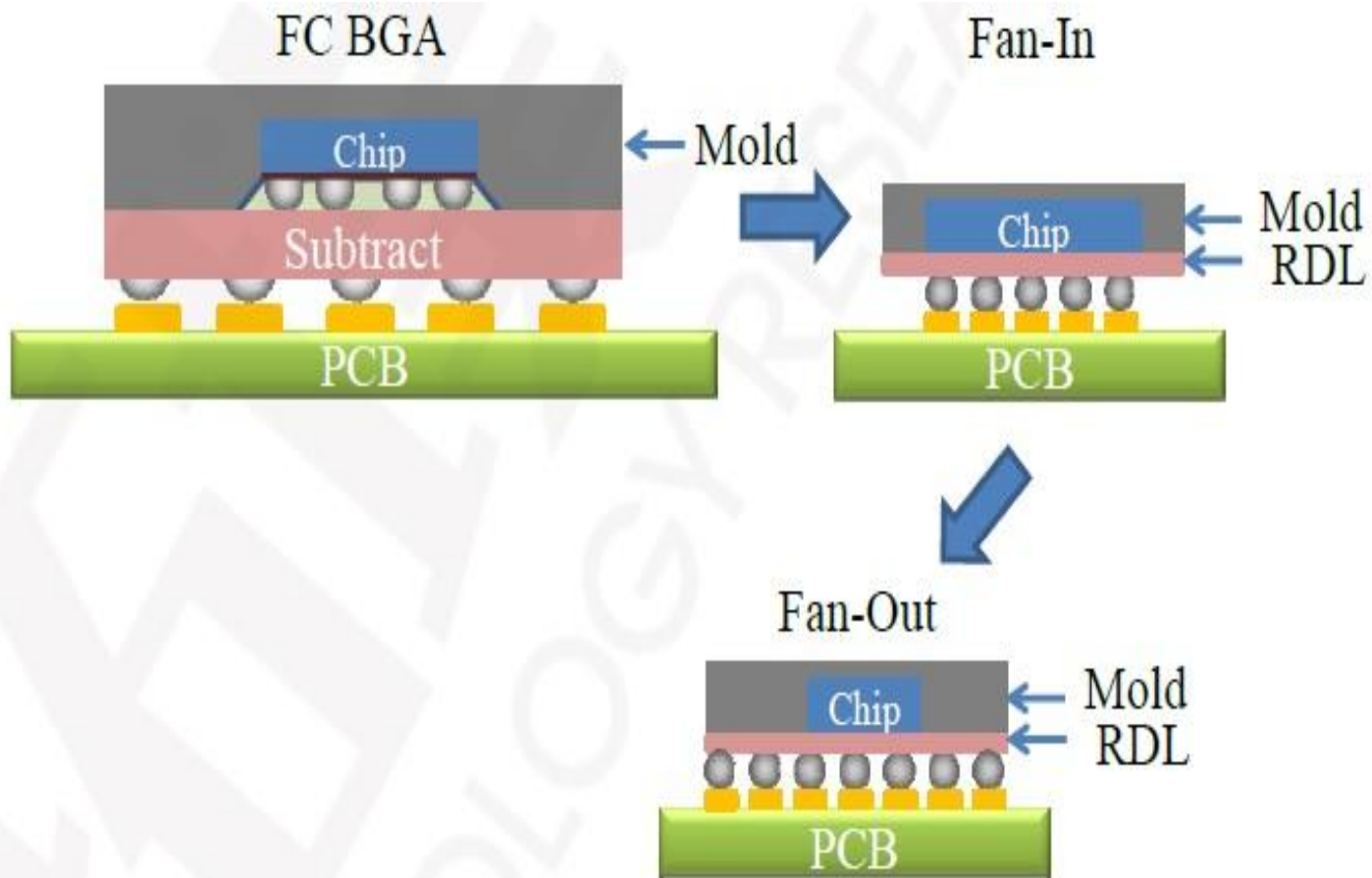
Advance Package

Packaging Type		Manufacturer		Application
SIP (system in package)		OSAT	ASE	Smart phone IoT Mobile
			USI	
		Module house	Hon Hai Pegatron	
			Component	
WLP (wafer level package)	InFO	Foundry	TSMC	Smart Phone
	CoWoS		TSMC	
Flip chip	2D/3D	OSAT	ASE	Smart Phone IoT Mobile
			Spil	
			Amkor	
			JCET	
			Powertech	

System in Package (SiP)

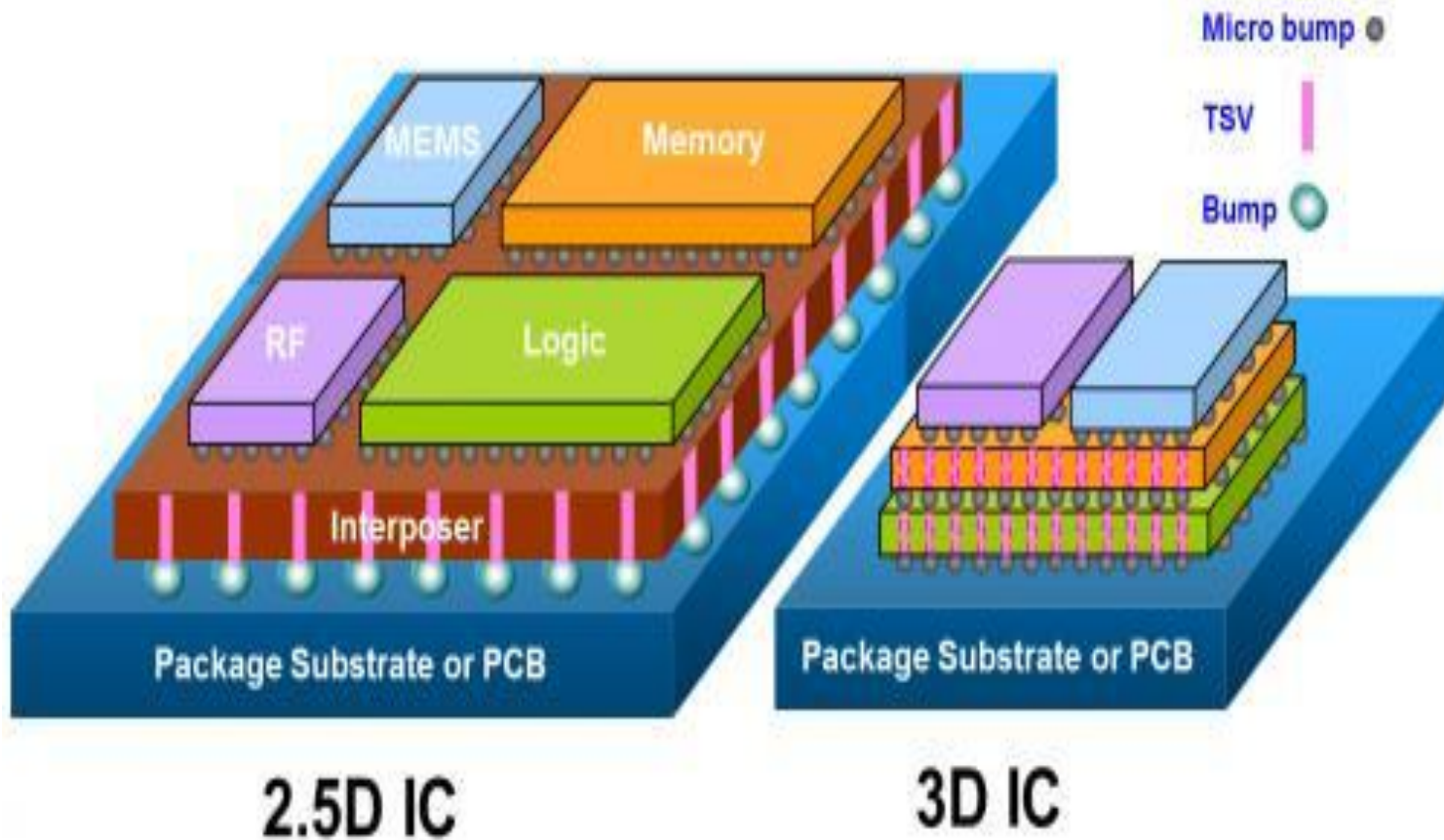


Flip-chip & wafer-level packaging



Source: TRI

2.5D & 3D IC Packaging



TSMC's 3DFabric

TSMC 3DFabric™



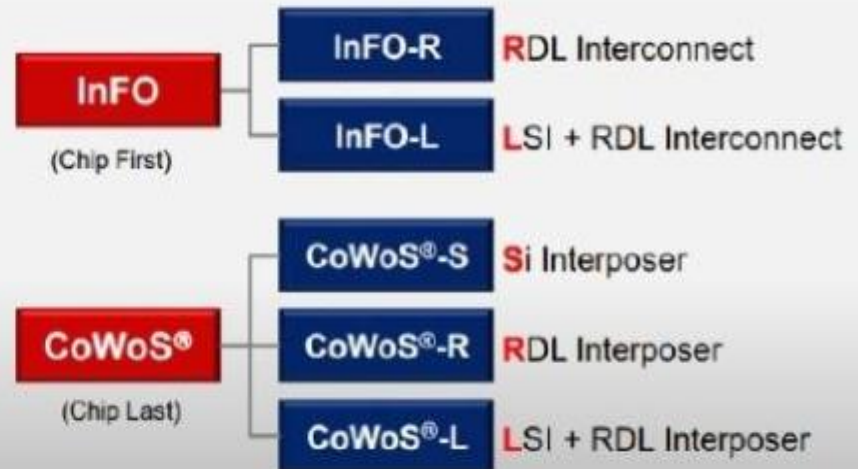
Chip Stacking (FE 3D)



SoIC: System on Integrated Chips

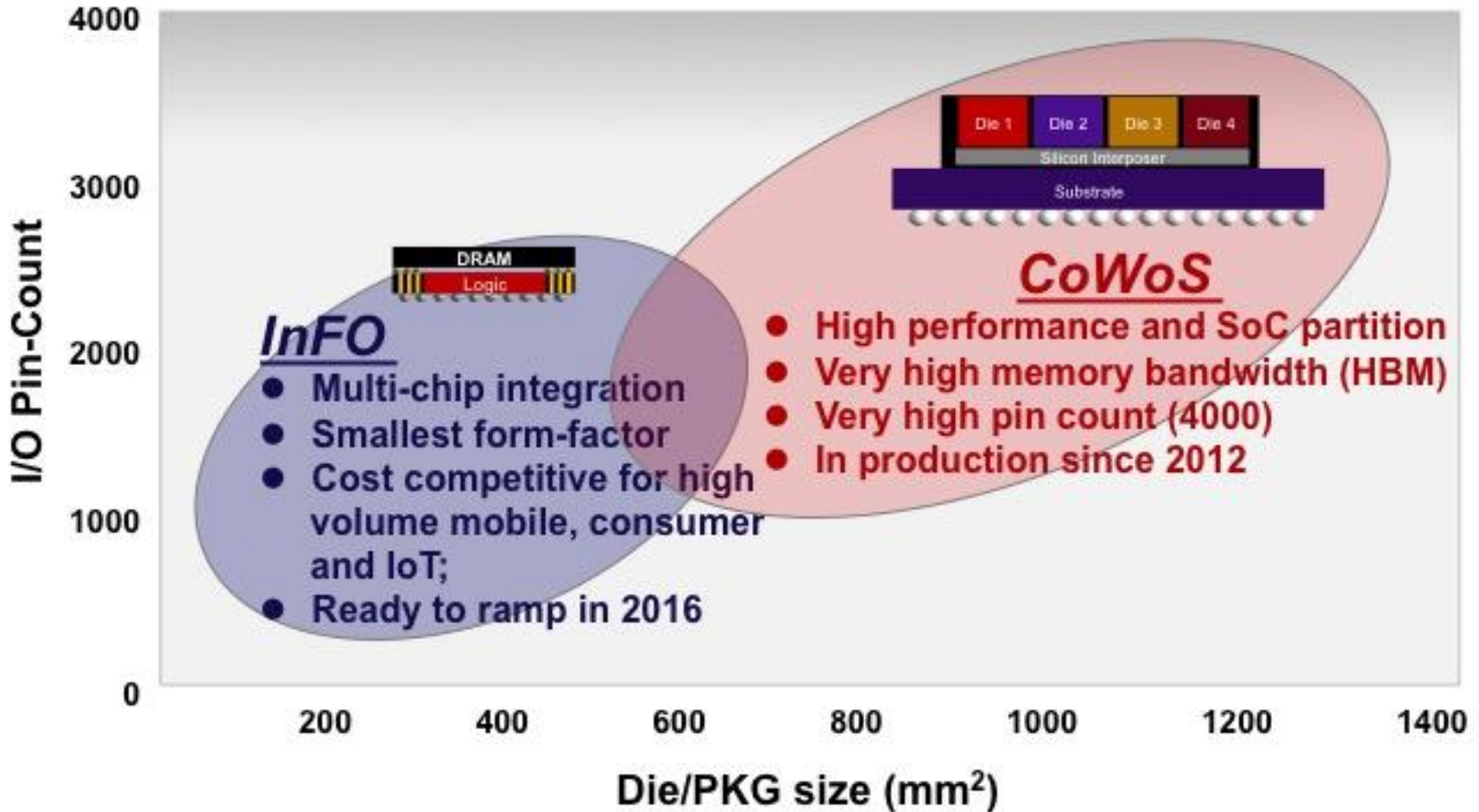
Source: TSMC

Advanced Packaging (BE 3D)



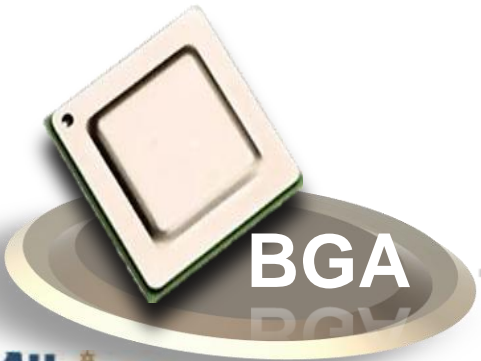
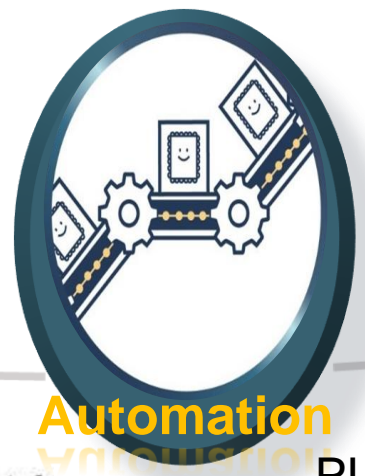
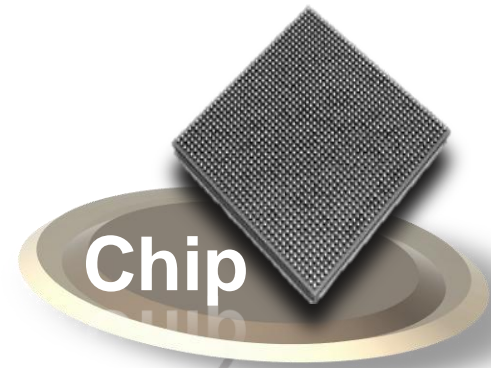
InFO: Integrated Fan-Out
CoWoS: Chip on Wafer on Substrate
RDL: Redistribution Layer
LSI: Local Si Interconnect

TSMC's InFO & CoWoS



Source: TSMC

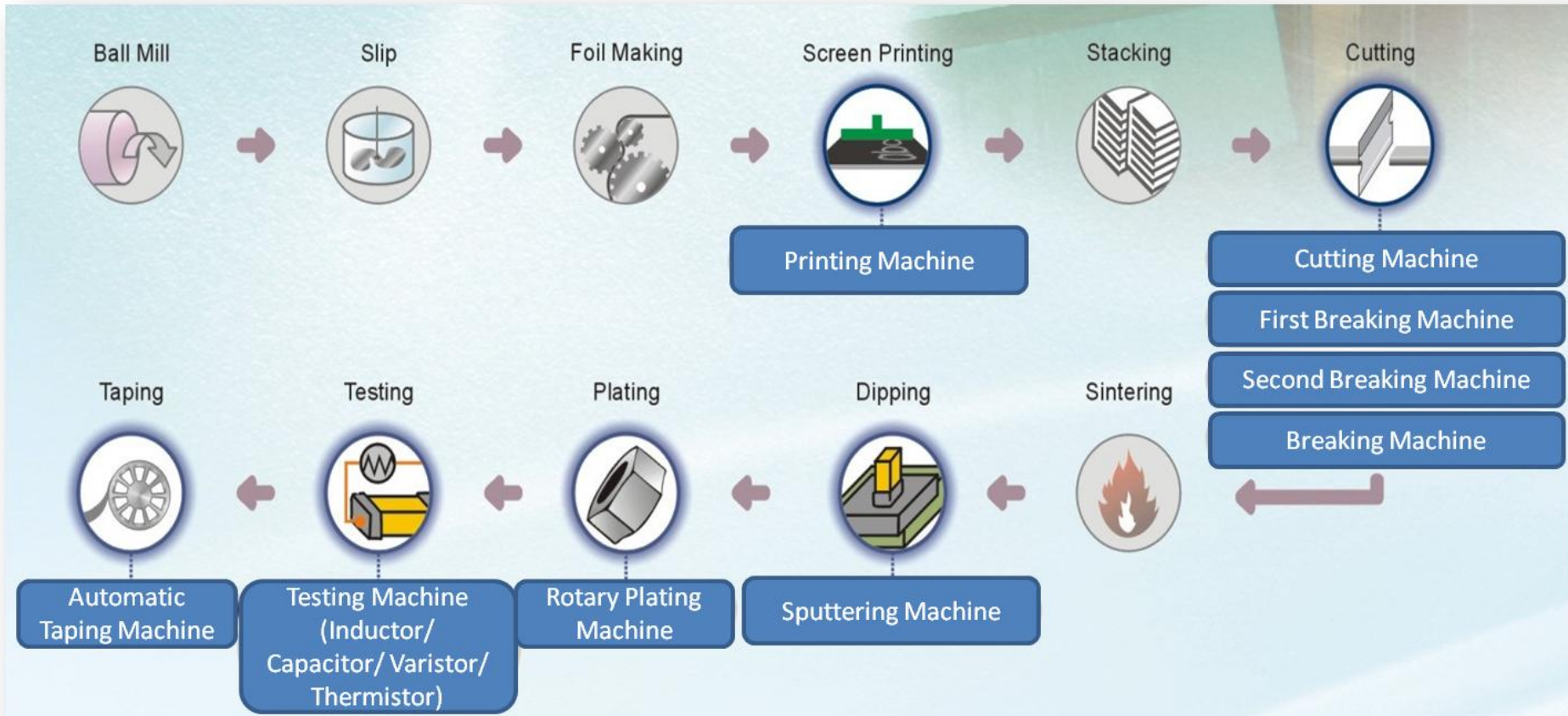
Equipment for Flip Chip



Flip Chip in Package Process



Passive Component Production Process



Product Portfolio

PC

Capacitive & Inductive Cutting Machine



Wire wound power inductor



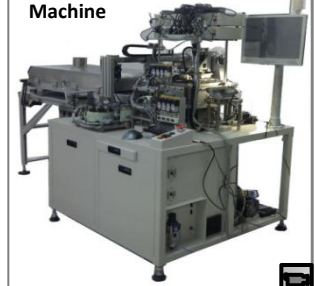
Unline Wire Winding Machine



Rotary-type Plating Machine



Power Inductor Dispenser Machine



IC

Dual-track Ball Grid Array Ball Mounting Machine



Under Fill



Load/Unload Equipment



Wafer Level CSP Die Sorter



Dispenser



LED



























LED Test Taping Machine



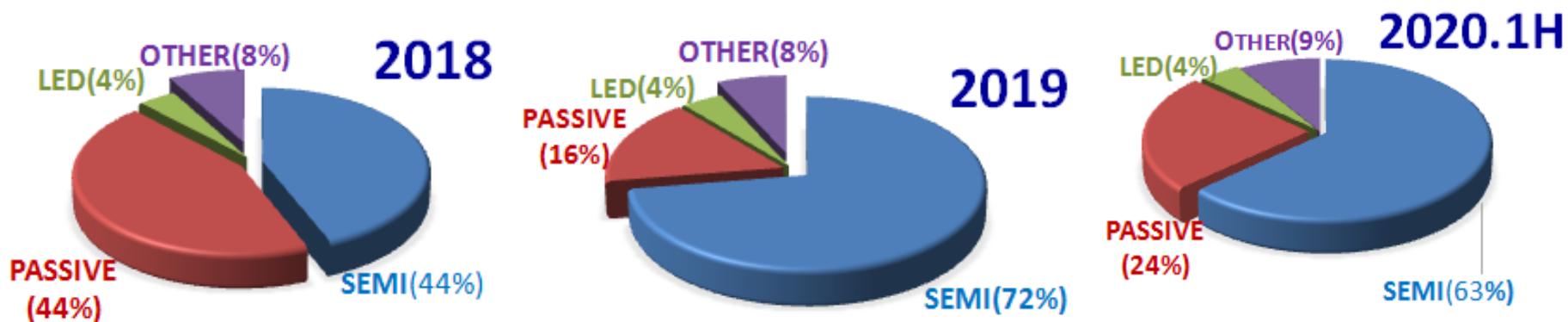
LED Test Sorting Machine



Customer Base

Semiconductor	Passive Component	LED
       	           	     

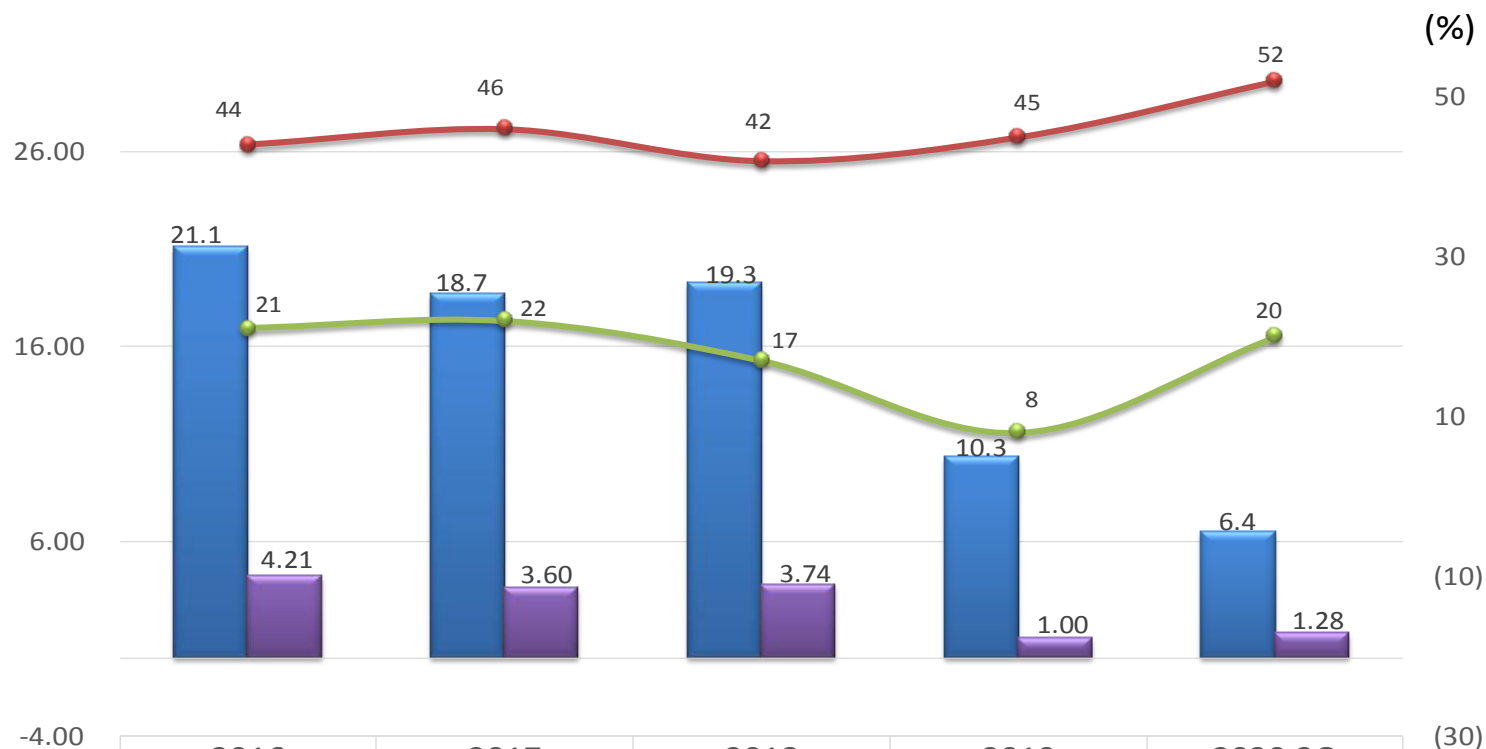
Revenue Breakdown



NT\$100M

	2018		2019		2020.1H	
SEMI	8.46	44%	7.48	72%	4.06	63%
PASSIVE	8.49	44%	1.70	16%	1.53	24%
LED	0.77	4%	0.43	4%	0.28	4%
OTHER	1.54	8%	0.71	8%	0.56	9%
TOTAL	19.26	100%	10.32	100%	6.43	100%

Financial Highlights



	2016	2017	2018	2019	2020.2Q
Sales(NT\$100mn)	21.1	18.7	19.3	10.3	6.4
EPS(NT\$)	4.21	3.60	3.74	1.00	1.28
GM(%)	44	46	42	45	52
OPM(%)	21	22	17	8	20



Q & A



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